



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD50R2K0CE	Issued	25. June 2021
MA#	MA005556791		
Package	PG-TO252-3-344	Weight*	321.63 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.070	0.33	0.33	3328	3328
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.02		165	
	non noble metal	iron	7439-89-6	0.177	0.06		551	
	non noble metal	copper	7440-50-8	176.899	55.01	55.09	550016	550732
wire	non noble metal	aluminium	7429-90-5	0.171	0.05	0.05	531	531
encapsulation	organic material	carbon black	1333-86-4	0.690	0.21		2144	
	plastics	epoxy resin	-	18.622	5.79		57899	
	inorganic material	silicondioxide	60676-86-0	118.628	36.88	42.88	368838	428881
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11919	11919
solder	non noble metal	tin	7440-31-5	0.030	0.01		92	
	noble metal	silver	7440-22-4	0.037	0.01		115	
	non noble metal	lead	7439-92-1	1.416	0.44	0.46	4402	4609
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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